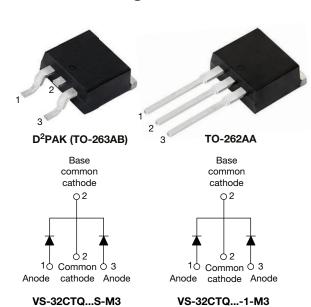


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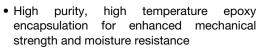
High Performance Schottky Rectifier, 2 x 15 A



PRIMARY CHARACTERISTICS						
I _{F(AV)}	2 x 15 A					
V_{R}	25 V, 30 V					
V _F at I _F	0.40 V					
I _{RM} typ.	97 mA at 125°C					
T _J max.	150 °C					
E _{AS}	13 mJ					
Package	D ² PAK (TO-263AB), TO-262AA					
Circuit configuration	Common cathode					

FEATURES

- 150 °C T_J operation
- · Low forward voltage drop
- High frequency operation





- Guard ring for enhanced ruggedness and long term reliability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

DESCRIPTION

The VS-32CTQ... Schottky rectifier series has been optimized for low reverse leakage at high temperature. The proprietary barrier technology allows for reliable operation up to 150 °C junction temperature. Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

MAJOR RATINGS AND CHARACTERISTICS							
SYMBOL	CHARACTERISTICS	VALUES	UNITS				
I _{F(AV)}	Rectangular waveform	30	A				
V _{RRM}		25, 30	V				
I _{FSM}	t _p = 5 μs sine	900	A				
V _F	15 A _{pk} , T _J = 125 °C	0.40	V				
TJ	Range	-55 to +150	°C				

VOLTAGE RATINGS								
PARAMETER	SYMBOL	VS-32CTQ025S-M3 VS-32CTQ025-1-M3	VS-32CTQ030S-M3 VS-32CTQ030-1-M3	UNITS				
Maximum DC reverse voltage	V _R	25	30	V				
Maximum working peak reverse voltage	V_{RWM}	25	30	V				



VS-32CTQ...S-M3, VS-32CTQ...-1-M3 Series

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ABSOLUTE MAXIMUM RATINGS								
PARAMETER	SYMBOL	TEST COND	ITIONS	VALUES	UNITS			
Maximum average forward current See fig. 5	I _{F(AV)}	50 % duty cycle at T _C = 115 °C	30					
Maximum peak one cycle non-repetitive		5 μs sine or 3 μs rect. pulse Following any rated load		900	Α			
surge current See fig. 7	I _{FSM}	10 ms sine or 6 ms rect. pulse	condition and with rated V _{RRM} applied	250				
Non-repetitive avalanche energy	E _{AS}	$T_J = 25 ^{\circ}\text{C}, I_{AS} = 1.20 \text{A}, L = 11 \text{C}$	13	mJ				
Repetitive avalanche current	I _{AR}	Current decaying linearly to zero Frequency limited by T_J maxim	-	3	Α			

ELECTRICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CO	NDITIONS	VALUES	UNITS		
		15 A	T _{.1} = 25 °C	0.49	V		
Maximum forward voltage drop	V _{FM} ⁽¹⁾	30 A	1J=25 C	0.58			
See fig. 1	VFM (1)	15 A	T _{.1} = 125 °C	0.40			
		30 A	1j = 125 C	0.53			
Maxima un vovarea la la cara a univent	I _{RM} ⁽¹⁾	T _J = 25 °C	V _B = Rated V _B	1.75	mA		
Maximum reverse leakage current	IRM (1)	T _J = 125 °C	V _R = nateu v _R	145			
Typical reverse leakage current	I _{RM} ⁽¹⁾	T _J = 125 °C	V _R = Rated V _R	97	mA		
Threshold voltage	V _{F(TO)}	T - T movimum		0.233	V		
Forward slope resistance	r _t	$T_J = T_J$ maximum		9.09	mΩ		
Maximum junction capacitance per leg	C _T	V _R = 5 V _{DC} (test signal range 100 kHz to 1 MHz), 25 °C		1300	pF		
Typical series inductance per leg	L _S	Measured lead to lead 5 mr	8.0	nΗ			
Maximum voltage rate of change	dV/dt	Rated V _R		10 000	V/µs		

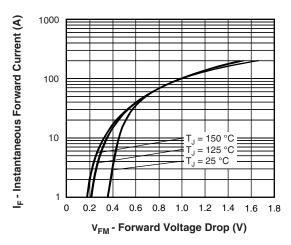
Note

 $^{^{(1)}}$ Pulse width < 300 μ s, duty cycle < 2 %

THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER		SYMBOL	TEST CONDITIONS	VALUES	UNITS			
Maximum junction and storage temperature range		T _J , T _{Stg}		-55 to +150	°C			
Maximum thermal resistance, junction to case per leg			DC operation See fig. 4	3.25	°C/W			
Typical thermal resistance, case to heatsink		R _{thCS}	Mounting surface, smooth and greased	0.50	C/VV			
Approximate weight				2	g			
Approximate weight				0.07	OZ.			
Mounting torque	minimum			6 (5)	kgf · cm			
Mounting torque	maximum			12 (10)	(lbf \cdot in)			
			Case style D ² PAK (TO-263AB)	32CT0	Q025S			
Marking device			Case style D-PAK (TO-203AB)		Q030S			
			Coop ot do TO 262AA	32CTC	025-1			
			Case style TO-262AA		030-1			

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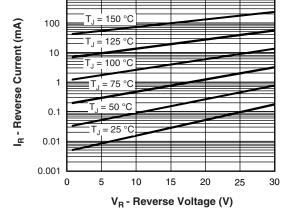


Fig. 1 - Maximum Forward Voltage Drop Characteristics

Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

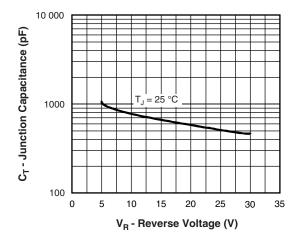


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

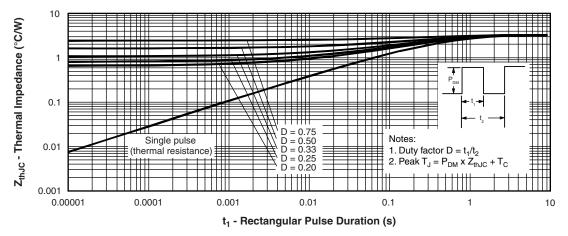


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

Allowable Case Temperature (°C)

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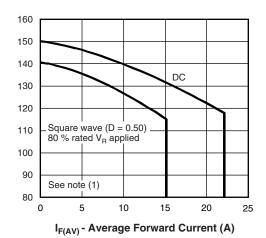


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

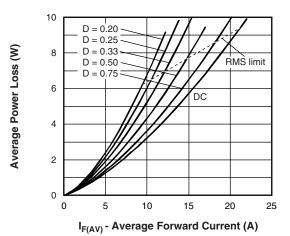


Fig. 6 - Forward Power Loss Characteristics

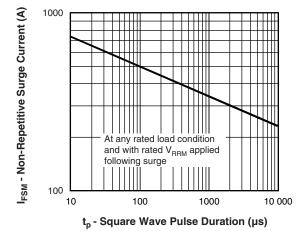


Fig. 7 - Maximum Non-Repetitive Surge Current

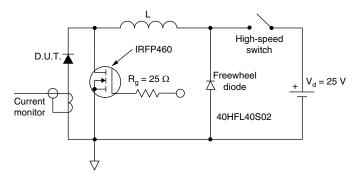


Fig. 8 - Unclamped Inductive Test Circuit

Note

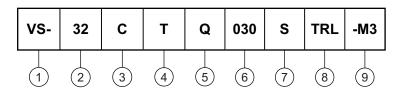
1) Formula used: T_C = T_J - (Pd + Pd_{REV}) x R_{th,JC}; Pd = forward power loss = I_{F(AV)} x V_{FM} at (I_{F(AV)}/D) (see fig. 6); Pd_{REV} = inverse power loss = V_{R1} x I_R (1 - D); I_R at V_{R1} = 80 % rated V_R

VS-32CTQ...S-M3, VS-32CTQ...-1-M3 Series

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ORDERING INFORMATION TABLE

Device code



Vishay Semiconductors product

2 - Current rating (30 A)

3 - Circuit configuration: C = common cathode

4 - T = TO-220

Schottky "Q" series

Voltage ratings 025 = 25 V 030 = 30 V

7 - • S = D²PAK (TO-263AB)

• -1 = TO-262AA

8 - • None = tube

• TRL = tape and reel (left oriented - for D²PAK (TO-263AB) only)

• TRR = tape and reel (right oriented - for D²PAK (TO-263AB) only)

9 - -M3 = halogen-free, RoHS-compliant, and termination lead (Pb)-free

ORDERING INFORMATION							
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION					
VS-32CTQ025S-M3	50	Antistatic plastic tubes					
VS-32CTQ025STRL-M3	800	13" diameter plastic tape and reel					
VS-32CTQ025STRR-M3	800	13" diameter plastic tape and reel					
VS-32CTQ030S-M3	50	Antistatic plastic tubes					
VS-32CTQ030STRL-M3	800	13" diameter plastic tape and reel					
VS-32CTQ030STRR-M3	800	13" diameter plastic tape and reel					
VS-32CTQ025-1-M3	50	Antistatic plastic tubes					
VS-32CTQ030-1-M3	50	Antistatic plastic tubes					

LINKS TO RELATED DOCUMENTS					
Dimensions	D ² PAK (TO-263AB)	www.vishay.com/doc?96164			
Differsions	TO-262AA	www.vishay.com/doc?96165			
Ded and the lafe weetler	D ² PAK (TO-263AB)	www.vishay.com/doc?95444			
Part marking information	TO-262AA	www.vishay.com/doc?95443			
Packaging information		www.vishay.com/doc?96424			



Vishay Semiconductors

D²PAK

DIMENSIONS in millimeters and inches



SYMBOL	MILLIM	ETERS	INC	HES	NOTES		SYMBOL MILLIMETERS		S INCHES		NOTES	
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES	NOIES	STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010			Е	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4		е	2.54	BSC	0.100	BSC	
b2	1.14	1.78	0.045	0.070			Н	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
С	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065			L3	0.25	BSC	0.010	BSC	
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC® outline TO-263AB

Vishay Semiconductors

TO-262

DIMENSIONS in millimeters and inches



SYMBOL	MILLIN	METERS	INC	INCHES			
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES		
Α	4.06	4.83	0.160	0.190			
A1	2.03	3.02	0.080	0.119			
b	0.51	0.99	0.020	0.039			
b1	0.51	0.89	0.020	0.035	4		
b2	1.14	1.78	0.045	0.070			
b3	1.14	1.73	0.045	0.068	4		
С	0.38	0.74	0.015	0.029			
c1	0.38	0.58	0.015	0.023	4		
c2	1.14	1.65	0.045	0.065			
D	8.51	9.65	0.335	0.380	2		
D1	6.86	8.00	0.270	0.315	3		
E	9.65	10.67	0.380	0.420	2, 3		
E1	7.90	8.80	0.311	0.346	3		
е	2.54 BSC		0.100	BSC			
L	13.46	14.10	0.530	0.555			
L1	-	1.65	-	0.065	3		
L2	3.36	3.71	0.132	0.146			

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- 5) Controlling dimension: inches
- (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum), D1 (minimum) and L2 where dimensions derived the actual package outline

Revision: 11-Jul-2019 1 Document Number: 95419



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